

ABSTRACT OF THE DISCLOSURE

A dry-wet thermal management system for providing simultaneous spray cooling and dry cooling for a plurality of cards. The dry-wet thermal management system includes a chassis having a dry chamber and a spray chamber, a first opening within a rear portion of the chassis extending into the spray chamber, a second opening within the rear portion of the chassis extending into the dry chamber, and a main backplane secured and sealed to the rear portion of the chassis. Electronic cards may be electrically coupled within sockets of the main backplane within both the dry chamber and the spray chamber. The cards within the spray chamber are typically high heat flux components with increased cooling requirements and the cards within the dry chamber are typically low heat flux components with reduced cooling requirements. A spray cool system is within the spray chamber and a dry cool system is within the dry chamber.